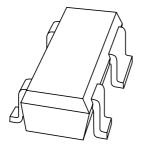
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# BGA2002 silicon MMIC amplifier

Objective specification
File under Discrete Semiconductors, SC14

1998 Sep 01





# silicon MMIC amplifier

#### **BGA2002**

#### **FEATURES**

- Low current, low voltage
- · Very high power gain
- Low noise figure
- · Integrated temperature compensated biasing
- Supply and RF output pin combined

#### **APPLICATIONS**

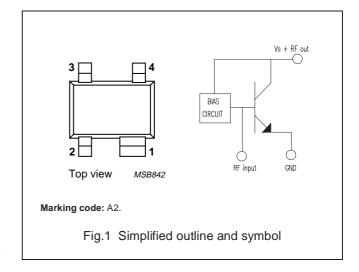
- · RF front end
- Wideband applications, e.g. analog and digital cellular telephones, cordless telephones (PHS, DECT, etc.)
- · Radar detectors
- · Low noise amplifiers
- Satellite television tuners (SATV)
- · High frequency oscillators.

#### **DESCRIPTION**

Silicon MMIC amplifier consisting of an NPN double polysilicon transistor with integrated biasing for low voltage applications in a plastic, 4-pin dual-emitter SOT343R package.

#### **PINNING SOT343R**

| PIN | DESCRIPTION                |
|-----|----------------------------|
| 1   | ground                     |
| 2   | RF input                   |
| 3   | ground                     |
| 4   | V <sub>S</sub> + RF output |



#### **QUICK REFERENCE DATA**

| SYMBOL         | PARAMETER           | CONDITIONS  | TYP. | MAX. | UNIT |
|----------------|---------------------|---|------|------|------|
| Vs             | DC supply voltage   | RF input AC coupled   | _    | 4.5  | V    |
| I <sub>S</sub> | DC supply current   | V <sub>S</sub> = 2.5 V; RF input AC coupled                             | 10   | _    | mA   |
| MSG            | maximum stable gain | V <sub>S</sub> = 2.5 V; f = 2 GHz; T <sub>amb</sub> = 25 °C             | 19   | _    | dB   |
| F              | noise figure        | $V_S = 2.5 \text{ V}$ ; $f = 2 \text{ GHz}$ ; $\Gamma_S = \Gamma_{opt}$ | 2.0  | _    | dB   |

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#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL           | PARAMETER                      | CONDITIONS                       | MIN. | MAX. | UNIT |
|------------------|--------------------------------|----------------------------------|------|------|------|
| Vs               | supply voltage                 | RF input AC coupled              | _    | 4.5  | V    |
| I <sub>S</sub>   | supply current (DC)            | forced by DC voltage on RF input | _    | 30   | mA   |
| P <sub>tot</sub> | total power dissipation        | up to T <sub>s</sub> = 100 °C    | _    | 135  | mW   |
| T <sub>stg</sub> | storage temperature            |                                  | -65  | +150 | °C   |
| Tj               | operating junction temperature |                                  | _    | 150  | °C   |

#### THERMAL CHARACTERISTICS

| SYMBOL              | PARAMETER   | VALUE | UNIT |
|---------------------|---|-------|------|
| R <sub>th j-s</sub> | thermal resistance from junction to soldering point | 350   | K/W  |

#### **CHARACTERISTICS**

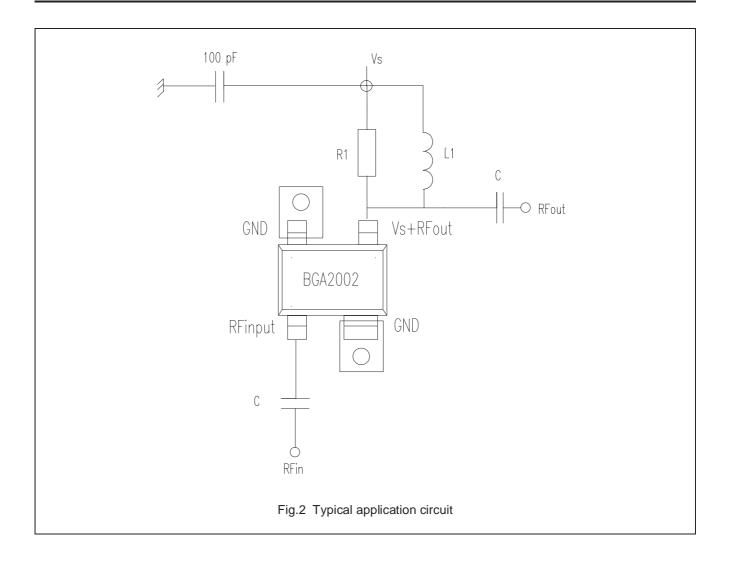
RF input AC coupled;  $T_j$  = 25 °C; unless otherwise specified.

| SYMBOL         | PARAMETER            | CONDITIONS  | MIN. | TYP. | MAX. | UNIT |
|----------------|----------------------|---|------|------|------|------|
| I <sub>S</sub> | supply current       | V <sub>S</sub> = 1 V  | _    | 1.3  | _    | mA   |
|                |                      | V <sub>S</sub> = 2.5 V  | _    | 10   | _    | mA   |
|                |                      | V <sub>S</sub> = 4.5 V  | _    | 19   | _    | mA   |
| MSG            | maximum stable gain  | $V_S = 2.5 \text{ V}; I_S = 10 \text{ mA}; f = 900 \text{ MHz}$                               | _    | 25   | _    | dB   |
|                |                      | $V_S = 2.5 \text{ V}; I_S = 10 \text{ mA}; f = 2 \text{ GHz}$                                 | _    | 19   | _    | dB   |
| $ S_{21} ^2$   | insertion power gain | $V_S = 2.5 \text{ V}; I_S = 10 \text{ mA}; f = 900 \text{ MHz}$                               | _    | 21   | _    | dB   |
|                |                      | $V_S = 2.5 \text{ V}; I_S = 10 \text{ mA}; f = 2 \text{ GHz}$                                 | _    | 16   | _    | dB   |
| F              | noise figure         | $V_S = 2.5 \text{ V}; I_S = 10 \text{ mA}; f = 900 \text{ MHz};$<br>$\Gamma_S = \Gamma_{opt}$ | _    | 1.9  | _    | dB   |
|                |                      | $V_S$ = 2.5 V; $I_S$ = 10 mA; $f$ = 2 GHz; $\Gamma_S$ = $\Gamma_{opt}$                        | _    | 2.0  | _    | dB   |

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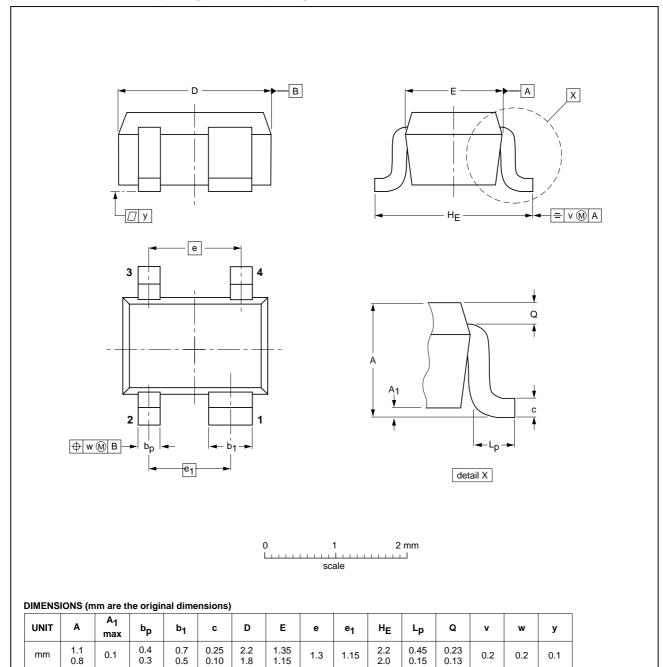
# silicon MMIC amplifier

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#### **PACKAGE OUTLINE**

#### Plastic surface mounted package; reverse pinning; 4 leads

SOT343R



| OUTLINE | REFERENCES |       |      | EUROPEAN ISSUE DATE |            |            |  |
|---------|------------|-------|------|---------------------|------------|------------|--|
| VERSION | IEC        | JEDEC | EIAJ |                     | PROJECTION | ISSUE DATE |  |
| SOT343R |            |       |      |                     |            | 97-05-21   |  |

1.15

0.2

0.2

0.1

1.3

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mm

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#### **DEFINITIONS**

| Data Sheet Status         |   |
|---------------------------|---|
| Objective specification   | This data sheet contains target or goal specifications for product development.       |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification     | This data sheet contains final product specifications.                                |
| Limiting values           |   |

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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